

# RKS1500DKK

Silicon Epitaxial Planar Diode for UHF/VHF tuner Band Switch

REJ03G0400-0100

Rev.1.00

Oct 14, 2004

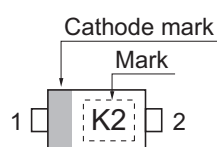
## Features

- Low forward resistance. ( $r_f = 0.7 \Omega$  max)
- Super small Flat Package (SFP) is suitable for surface mount design.

## Ordering Information

| Type No.   | Laser Mark | Package Code |
|------------|------------|--------------|
| RKS1500DKK | K2         | SFP          |

## Pin Arrangement



1. Cathode
2. Anode

## Absolute Maximum Ratings

(Ta = 25°C)

| Item                 | Symbol    | Value       | Unit |
|----------------------|-----------|-------------|------|
| Reverse voltage      | $V_R$     | 35          | V    |
| Power dissipation    | $P_d$     | 150         | mW   |
| Junction temperature | $T_j$     | 125         | °C   |
| Storage temperature  | $T_{stg}$ | -55 to +125 | °C   |

## Electrical Characteristics

(Ta = 25°C)

| Item               | Symbol | Min | Typ | Max | Unit     | Test Condition                             |
|--------------------|--------|-----|-----|-----|----------|--------------------------------------------|
| Reverse current    | $I_R$  | —   | —   | 50  | nA       | $V_R = 25\text{ V}$                        |
| Forward voltage    | $V_F$  | —   | —   | 1.0 | V        | $I_F = 10\text{ mA}$                       |
| Capacitance        | $C$    | —   | —   | 1.2 | pF       | $V_R = 6\text{ V}$ , $f = 1\text{ MHz}$    |
| Forward resistance | $r_f$  | —   | —   | 0.7 | $\Omega$ | $I_F = 2\text{ mA}$ , $f = 100\text{ MHz}$ |

Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

2. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

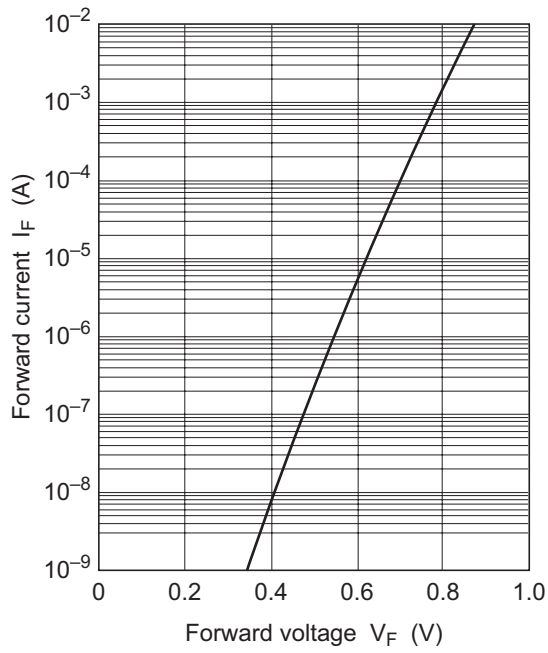


Fig.1 Forward current vs. Forward voltage

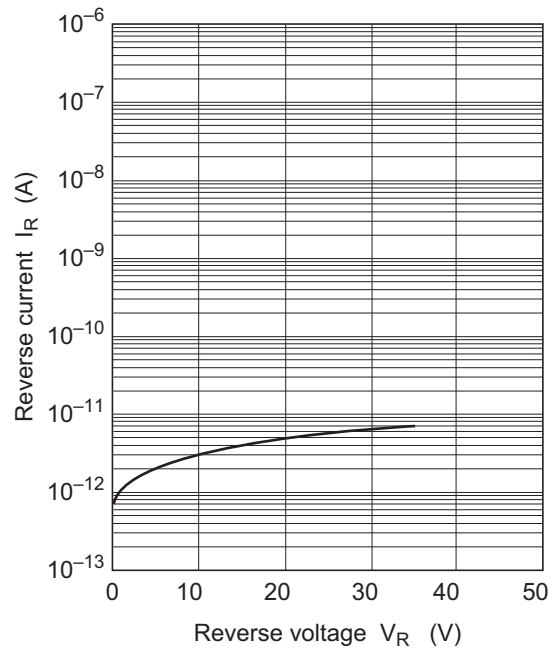


Fig.2 Reverse current vs. Reverse voltage

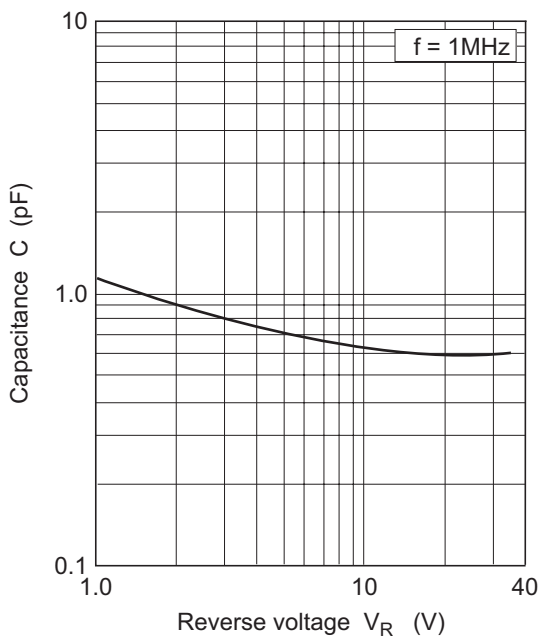


Fig.3 Capacitance vs. Reverse voltage

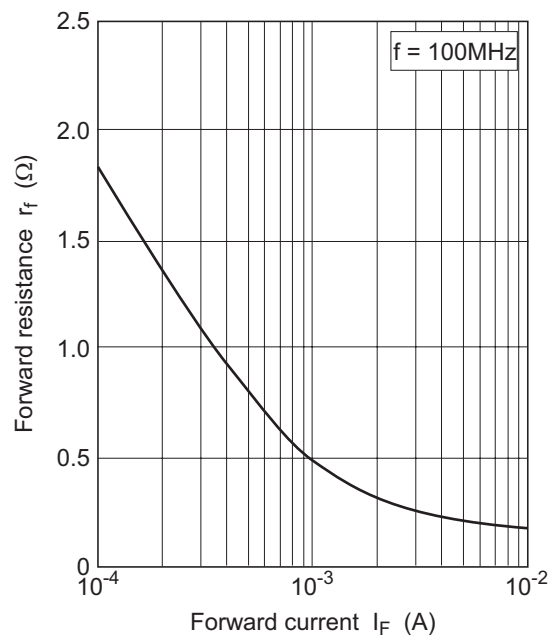
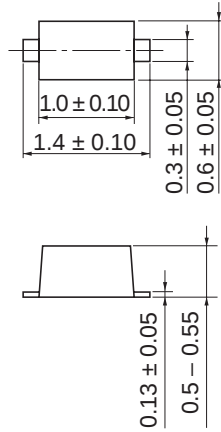


Fig.4 Forward resistance vs. Forward current

## Package Dimensions

As of January, 2003  
Unit: mm



|                        |          |
|------------------------|----------|
| Package Code           | SFP      |
| JEDEC                  | —        |
| JEITA                  | —        |
| Mass (reference value) | 0.0010 g |

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